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S32K396-BGA-DC1

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User manual

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Document information

Information	Content					
Keywords	S32K396, EVB, User Manual					
Abstract	Information necessary for work with S32K396-BGA EVB					

Introduction

This document describes the features of S32K396 289MapBGA Evaluation board (EVB).

It provides guidance to developers about how the board should be utilized and describes its features.

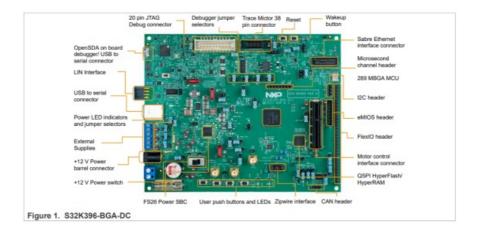
The S32K396 MCU series includes S32K36x, S32K37x, and S32K39x. The S32K39 MCUs extend the highperformance capabilities of S32K37 with two programmable motor control co-processors and extended analogue capabilities. S32K396 is used throughout this document to cover all the variants of the MCU.

This S32K396 289MapBGA Daughter card (DC) is capable of operating standalone and can be extended by the S32X-MB Motherboard (MB) that is common also for S32Z/E family. MB provides another source of power supply for S32K396 MCU as well as extension of DC card functionality with more physical interfaces and user headers. Both boards are connected through the mating connectors (MB-DC).

S32K396 DC EVB overview

Daughter card is populated with several communication interfaces, user LEDs, push buttons, and headers (see Table 1). Several options for debug interfaces are enabled. JTAG is configured as a default debug interface.

Apart from that, the OpenSDA and Trace interfaces are enabled as well. DC card supports one Motor control interface and connector to attach EVB with Ethernet PHY. Three other options are also supported to deliver power supply for all the domains. EVB can be used standalone where power supply is provided from the 12V barrel connector and further provided by FS26 PMIC, or the supplies could be connected independently using the screw connector. In case of using MB to extend the functionality of the DC card, supply could be generated from MB on board regulators.



The daughtercard (DC) is capable of operating standalone and its functionality can be extended by the motherboard (MB). Both boards are connected through the mating

connectors (MB-DC).



Table 1. Overview of S32K396 EVB interfaces

Interface	S32K396-BGA-DC1	S32X-MB
CAN	1x PHY (CAN0)	4x PHY (CAN0, CAN1, CA N3, CAN4)
LIN	2 x UART to LIN converter (UART2, UART3)	2 x UART to LIN converter (UART2, UART3)
Ethernet	1x connector (no PHY)	_
USB/UART	2x (UART2, UART0)	1x (UART 1)
MC connector	1x	1x
Zipwire	1x	_
QSPI	1x	_
MSC	1x (headers – LPUART_M SC, DSPI)	_
I2C	2x (1x USB-serial: I2C0, 1 x header: I2C1)	_
FlexIO	Header	_
eMIOS	Header	_
User LED	3x (PTD4, PTD5, PTH7)	4x

User push button	4x (PTE21,PTG0, PTG1, P TG2)	4x
Potentiometer	_	1x
BMS interface	1 x header (J59, LPSPI2, L PSPI3)	_

Start-up

3.1 PMIC mode configuration

FS26 supports two modes of operations, Normal and Debug, based on the jumper configuration (see Table 2 for the jumper configuration). When Normal mode is selected, FS26 watchdog is active and when it is not serviced in the timely manner, it issues reset to S32K396 by asserting the RESET_b signal. Based on the FS26 configuration after a couple of resets, the FS26 stops generating the MCU power supply.

Table 2. FS26 mode select

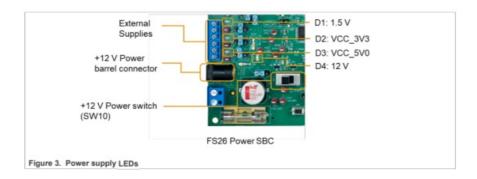
FS26 mode	J10	J11
Normal	Open	Short
Debug (default)	Short	Open

3.2 Power up

Follow these steps to power supply the board using an external 12V adapter:

- 1. Following the ESD standard procedure when unpacking the S32K396-BGA-DC1.
- 2. Make sure that the jumpers for power distribution and MCU power supply are configured correctly according to the intended power scheme.
- 3. Configure J4 (5.0V), J7 (3.3V), and J6 (1.5 V) to get the power from the PMIC (position 2-4).
- Connect the necessary cables between the host PC and EVB prior to applying 12V power to the EVB.
- 5. Apply the 12V power to EVB and flip the SW10 to ON position (right \rightarrow left).

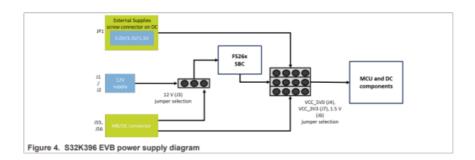
- 6. When power is applied to the DC card, four green LEDs show the presence of the supply voltages as follows:
 - LED D4 indicates that the 12.0V supply is connected to the DC correctly.
 - LED D3 indicates that the VCC 5V0 supply is on.
 - LED D2 indicates that the VCC_3V3 supply is on.
 - LED D1 indicates that the 1.5V supply is on.



Power supply

There are three ways how the EVB can be supplied:

- External 12V/2A power supply
 - FS26 PMIC generates all necessary power supplies:
 - VCC_5V0 supply for analog and digital I/O (LDO2OUT)
 - VCC_3V3 supply for digital I/O (LDO1OUT)
 - 1.5 V supply to generate 1.1 V for core and logic (CORE)
 - VREF 5V supply for analog references (VREF)
- External 5.0 V, 3.3 V, and 1.5 V power supplies over the screw type connectors [default]
- From the MB (12.0 V, 5.0 V, 3.3V, 1.5V)



4.1 EVB main 12 V power supply

Main supply for the daughtercard 12V can be supplied either from MB or DC supply

connectors. To distribute the 12V power from either source further to the DC components, the SW10 must be in 1-2 position.

Table 3. DC 12V supply source selection

Source of the 12V	J3
DC card connectors, provided either from J1 or J2	1-2 (default)
Motherboard (through J55A)	2-3



VCC_12V is further used to supply VBAT_LIN and as a supply for Ethernet PHY Sabre board that can be connected through connector J53.

Note: SW10 has to be always in position 1-2 to enable 12V propagation to the DC card interfaces, also in the case that 12V is provided from the motherboard (J3 shorted in position 2-3).

Table 4. Main supply connector overview

Connector Reference		Description
12V	DC: J1	This connector should be used to connect the supplied wall-plug main adapter. Note: if a replacement or alternative adapter is used, you must ensure that the 2.1mm plug uses the correct polarization.

12V GND	DC: J2	This can be used to connect a bare wire lead to the EVB, typically from a laboratory power supply. The polarization of the connectors is clearly marked on the EVB. You must ensure correct connection.
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4.2 EVB VCC_5V0, VCC_3V3 power supply

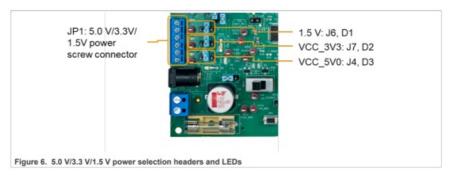
There are three options for getting these power supplies on the daughtercard. See the following tables for details.

Table 5. DC VCC_5V0 supply configuration

Source of VCC_5 V0	J4	Note
External power scr ew connector (JP1 pin 4)	1-2 (def ault)	Typically from a laboratory power supply. You must en sure correct connection, making sure GND is connect ed as well (JP1 pin 1 or 5).
MB through J56A	2-3	Ensure that J7 on MB is closed (1-2 short)
PMIC	2-4	_

Table 6. DC VCC_3V3 supply configuration

Source of VCC_3 V3	J7	Note
External power scr ew connector (JP1 pin 3)	1-2 (def ault)	Typically from a laboratory power supply. You must en sure correct connection, making sure GND is connect ed as well (JP1 pin 1 or 5).
MB through J56A	2-3	Ensure that J9 on MB is closed (1-2 short).
PMIC	2-4	_

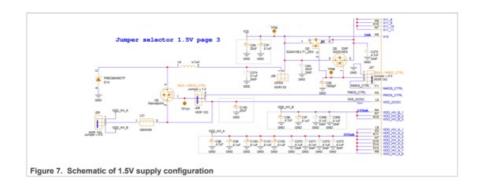


4.3 EVB 1.5 power supply

There are four options for getting 1.5V supply on the daughtercard.

Table 7. DC 1.5V supply configuration

1.5V source	J6	J26	J28	J29	Note							
External power screw connecto r (JP1 pin 2), ty pically from a la boratory power supply. Buck converter	1-2 (d efault)	Open (defaul t)	1-2 (def ault)	2-3 (de fault)	You must ensure correct connect ion, making sure GND is connect ed as well (JP1 pin 1 or 5). Note that for this option, J26 must be left open and J28 must be configured to 1-2 short. Make sure that J68 on MB is clo							
on MB through J56A	2-3											sed (1-2 short)
PMIC	2-4											
Internal SMPS	Open	1-2	2-3	1-2 (V DD_H V_ A)/2 -3(VDD _HV_B)	J29 selects the source voltage for the SMPS							



4.4 1.1 V core power supply settings

Ensure that J27 is closed for 2-3 (default) for all the operating conditions. This connects the NMOS_CTRL signal to the gate of external NFET that regulates 1.1 V core and logic supply down from 1.5 V.

4.5 VDD_HV_A and VDD_HV_B

The VDD_HV_A and VDD_HV_B domains can be supplied either from VCC_5V0 or from VCC_3V3. The default and preferred configuration is to supply VDD_HV_A from VCC_5V0 and VDD_HV_B from VCC_3V3.

The VDD_HV_A configuration is ensured by soldered blob R6, which is by default, shorted to position 1-3 (VCC_5V0).

The VDD_HV_B configuration is ensured by soldered blob R334, which is by default, shorted to position 1-2 (VCC_3V3).

See the following table for the possible configuration of the VDD_HV_A and VDD_HV_B power supply domain and peripheral limitations.

Table 8. VDD_HV_A and VDD_HV_B configuration

VDD_HV	_A	VDD_HV_B				Ethernet, QSPI, Zi
Voltage	R6	Voltage	R334	C, motor control (VDD_ HV_A)	pwire (VDD_HV_B)	
VCC_5 V0	1-3 (de fault)	VCC_3 V3	1-2 (default	Available	Available	
VCC_5 V0	1-3	VCC_5 V0	1-3	Available	Not available	

VCC_3 V3	1-2	VCC_3	1-2	Not available	Available
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4.6 VDD_DCDC

The VDD_DCDC domain can be supplied either from VDD_HV_A or VDD_HV_B. The selection for VDD_DCDC supply is available by configuration of J29.

Note that J29 must not be left open, one of the supplies must be selected all the time.

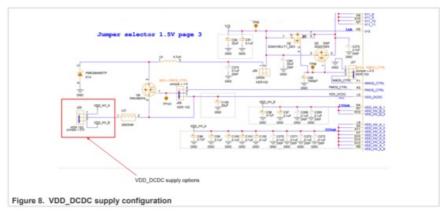


Table 9. VDD_DCDC supply configuration

VDD_DCDC source	J29
VDD_HV_A	1-2
VDD_HV_B	2-3 (default)

4.7 VDD LVDS

The VDD_LVDS domain can be supplied only by the 3.3 V source. It can be connected either to VDD_HV_B or VCC_3V3. J30 provides options for supply source selection. When Zipwire is not used, then the VDD_LVDS power domain can be left unconnected. Table 10. VDD_LVDS supply configuration

VDD_LVDS power	J30	Note
VCC_3V3	1-2	

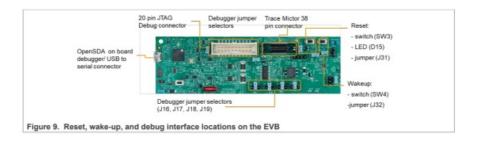
VDD_HV_B	2-3 (def ault)	Can be configured to this position only in case VDD_HV_B is supplied by 3.3 V
Unpowered	Open	Unpowered VDD_LVDS does not cause MCU reset (in this ca se, Zipwire cannot be used and VDD_ LVDS is signaled by fla g in the PMC.LVSC register)

4.8 VREFH

All voltage references of the MCU are connected to a single source, VREFH, which is recommended to be shorted with VDD_HV_A at the PCB level, or it can be supplied from PMIC. All VREFH_x pins must be supplied under all conditions and must not be left unconnected. Configuration is enabled by J63.

Table 11. VREFH source configuration

VREFH source	J63
PMIC VREF	1-2
VDD_HV_A	2-3 (default)



5.1 Reset, Wake, and LED indicator

On the DC card, there is a RESET switch (SW3) that provides a manual option to generate a reset signal to S32K396 MCU, which drives the RESET signal to reset the peripherals populated on the DC card. The RESET LED indicator (D15) is turned on (red light) when the RESET signal is active (J31 is closed).

The RESET_b signal is bidirectional and is routed to several interfaces on the DC card and to the MB through the MB DC interface connectors (see the following table).

Table 12. RESET_b signal routing

RESET_b connection	DC refere nce	Description
ETM Mictor Trace	J22	When closed, RESET_b is routed to the ETM Mictor Trace connector.
Arm JTAG debug	J23	When closed, RESET_b is routed to the Arm J TAG debug connector.
FS26	J12	When closed, RESET_b is routed to FS26.
Reset push button	J31	When closed, RESET_b is routed to SW3.
QSPI	J36	When closed, RESET_b is routed to the extern al QSPI memory.
Ethernet	J60	When closed, RESET_b is routed to external b oth Sabre connector and also Ethernet PHY on the MB.
USB/Serial	J67	When closed, RESET_b is routed from the US B/ Serial interface controlled GPIO to the MCU .

For the purpose of external wake-up source, the SW4 is routed to PTB19 that implements wake-up input functionality WKPU[38]. This is one of the ways to get the MCU wake-up from Standby mode.

5.2 Debug interface

On the DC card, there are three possible options for debugging sharing of the same signals. Signal routing for the particular debug interfaces are selectable by jumpers J16, J17, J18, and J19. See the description of configuration in the three options.

Table 13. Debug interface selection

Debug interface	J16, J17, J18, J19
Arm JTAG	2-4 (default)

Mictor Trace	2-3
OpenSDA	1-2

Table 14. DC card Debug interfaces overview

Connector		DC referen	Description	
20-pin Arm standard JTAG conn ector		J20	It supports the JTAG interface for acc essing ARM7 and ARM9 based devic es. For Cortex- Mx devices, it support s Serial Wire and JTAG interfaces for accessing all SWD, SWV, and JTAG signals available on a Cortex-Mx device.	
38-pin Arm ETM Mictor Connector		P1	The Mictor (Matched Impedance Connector) has been the standard way to connect a trace probe to an Arm targ et. Cortex-M7 supports 16-bit data trace using the Mictor connector. This is only available with DS-5 using a D STREAM debug and trace unit.	
OpenSDA		J15	Micro USB connector is used to connect to the onboard OpenSDA debug interface that bridges serial and debug communication between a USB host and the embedded target processor. The debug circuit is based on Kinet is MK65 MCU.	

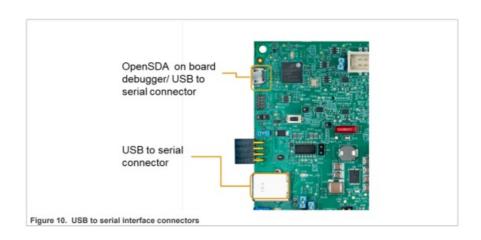
USB interface

On the DC card, LPUART0 is routed to the OpenSDA debug interface (J15) that supports also passing the USB to serial communication.

There is also MCP2221 (U32) interface for USB to UART/I2C conversion with GPIO functionality. It uses J64 USB-B type connector and it is connected to LPI2C0 instance and LPUART2 instance.

Table 15. USB to serial interfaces on DC

Interfac e	DC refe rence	Signal n	MCU port	Description
OpenS DA	J15	LPUART 0_RX	PTE10	UART Receive
	013	LPUART 0_TX	PTE11	UART Transmit
		LPUART 2_RX	PTH9	UART Receive
USB/se rial	J64 PTH8 UART Transmit		UART Transmit	
		LPI2C0_ SDA	PTF21	LPI2C Data I/O
		LPI2C0_ SCL	PTF20	LPI2C Clock I/O
		USB_RE SET	RESE T_B	When the J67 is populated, it can control the Reset signal



LIN interface

On the S32K396 DC is populated TJA1022 dual LIN transceiver capable to operate in both Master and Slave modes (jumper selectable: J50 and J51) and its outputs are connected to LIN interface connector J52. The MCU communicates with the driver over LPUART.

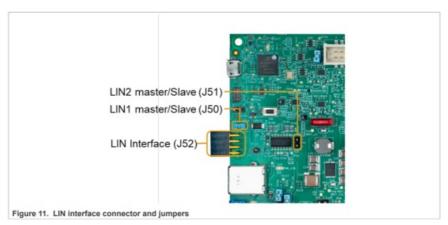


Table 16. LIN PHY configuration

LIN PHY Jumper position		Configuration
1 (150)	Open (default)	Slave
1 (J50)	close	Master
2 (151)	Open (default)	Slave
2 (J51)	Close	Master

Pinout of the LIN header is detailed in the following table.

Table 17. LIN interface connector J52

Pin number	Signal
1	GND
2	GND
3	NC
4	NC
5	VBAT_LIN
6	VBAT_LIN
7	LIN2
8	LIN1

The list of signals connected from MCU to LIN transceiver is provided in the following table. MCU signals for LIN1 are from the VDD_HV_A supply domain and signals for LIN2 from are from the VDD_HV_B domain.

Table 18. LIN connection from MCU to DC card LIN transceiver

	LIN interface	MCU Signal name	MCU port
1		LPUART3_RX	PTC20
		LPUART3_TX	PTE1

LIN interface	MCU Signal name	MCU port
2	LPUART2_RX	PTC12
	LPUART2_TX	PTC13

CAN interface

8.1 CAN interface on Daughtercard (DC)

On the S32K396 DC1 card is populated one CAN transceiver TJA1044GT. The CAN signals are routed on header J34 and are from the VDD_5V0 supply domain. The Standby mode for the PHY can be controlled by the J35 (Standby: 1-2; Normal (default): 2-3).

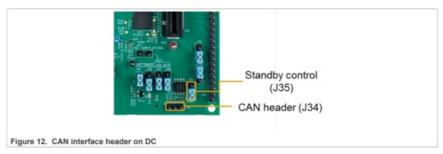


Table 19. CAN connection from MCU to DC card CAN transceiver

Signal name	MCU p	Description	Note
CAN0_TX	PTC21	CAN Tx chann	
CAN0_RX	PTC23	CAN Rx chann	

Ethernet interface

On the S32K396 EVB card, there is no Ethernet PHY but the Ethernet interface providing MII and/or RMII signals are routed to Sabre connector J53. Ethernet PHY Sabre expansion board can be plugged in there and used.

Table 20. Configuration of the Ethernet signals for the PHY interface on DC and MB

Signal	Configuration resistors on DC	DC SABRE interface enabl e: resistor configuration	MB TJA1103A P HY enable: resi stor configurati on
EMAC_MII_RMII_MDC	R521	DNP	Populated
EMAC_MII_RMII_MDIO	R530	DNP	Populated

EMAC_MII_RMII_TX_EN	R532	DNP	Populated
EMAC_MII_RMII_RX_ER	R522	DNP	Populated
EMAC_MII_CRS	J61	Open	J61 short 2-3
EMAC_MII_RXD3	R529	DNP	Populated
EMAC_MII_RMII_RXD[0]	R519	DNP	Populated
EMAC_MII_RMII_RXD[1]	R528	DNP	Populated
EMAC_MII_RXD2	R520	DNP	Populated
EMAC_MII_TXD3	R534	DNP	Populated
EMAC_MII_TXD2	R538	DNP	Populated
EMAC_MII_RMII_TXD[1]	R533	DNP	Populated
EMAC_MII_RMII_TXD[0]	R537	DNP	Populated
EMAC_MII_RMII_TX_CLK	R536	DNP	Populated
EMAC_MII_RX_CLK	R539	DNP	Populated
EMAC_MII_RMII_RX_DV	J61	Open	J61 short 1-2

The following figure depicts the SABRE interface J53 to connect TJA1103SDB SABRE development board.

Make sure resistors R266, R519, R520, R521, R522, R528, R529, R530, R532, R533, R534, R536, R537, R538, R539 are DNP and J61 is open to use the TJA1103SDB SABRE development board.

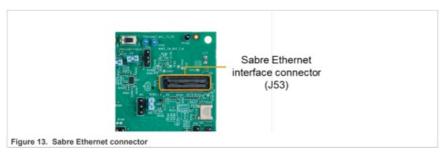


Table 21. Ethernet signals routed to the Sabre interface connector in DC

Signal	MCU p	Description
EMAC_MII_RMII_MDC	PTD17	ENET clock for control data transfer to PHY
EMAC_MII_RMII_MDIO	PTD16	ENET control data to/from PHY
EMAC_MII_RMII_TX_EN	PTE9	ENET transmit enable
EMAC_MII_RMII_RX_ER	PTC16	ENET receive error
EMAC_MII_COL	PTB27	ENET MII collision detected
EMAC_MII_RXD3	PTC15	ENET receive data (MII mode only)
EMAC_MII_RMII_RXD[0]	PTB23	ENET receive data
EMAC_MII_RMII_RXD[1]	PTB24	ENET receive data
EMAC_MII_RXD2	PTC14	ENET receive data (MII mode only)
EMAC_MII_TXD3	РТВ3	ENET transmit data (MII mode only)
EMAC_MII_TXD2	PTB28	ENET transmit data (MII mode only)
EMAC_MII_RMII_TXD[1]	PTB29	ENET transmit data
EMAC_MII_RMII_TXD[0]	PTC18	ENET transmit data
EMAC_MII_RMII_TX_CLK	PTC19	ENET transmit clock
EMAC_MII_RX_CLK	PTB26	ENET MII receive clock
EMAC_PPS1	PTD13	ENET 1588 timer channel
EMAC_PPS0	PTA26	ENET 1588 timer channel
EMAC_MII_CRS	PTB22	ENET MII carrier sense

	E	EMAC_MII_RMII_RX_DV	PTD14	ENET receive data valid
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Note Those signals are dedicated to the Ethernet interface and are routed to the Sabre connector.

QSPI interface

On the DC card there is populated S71KL512SC0 3.0V 512 Mb HyperFlash and 64Mb HyperRAM in multichip package. Selection of the target memory is done by the corresponding chip select signal. The memory is connected to the QSPI interface of the S32K396 MCU that features only one chip select, so the selection is done by soldered resistor R328 (1-2 by default, selecting Hyper Flash).

Table 22. QSPI memory chip select configuration

Selected me mory	R328	Description
Hyper Flash	1-2 (default)	QSPI_PCSFA is connected to CS1 pin of extern al memory
Hyper RAM	2-3	QSPI_PCSFA is connected to CS2 pin of extern al memory

There is a level shifter used only for the RESET_b signal because this pin is supplied from the VDD_HV_A domain. The reset signal can be disconnected from QSPI memory by header J36 (default close).

Warning

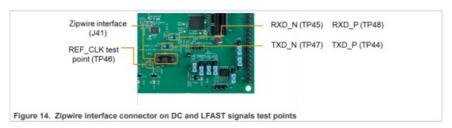
QSPI interface is supplied from the VDD_HV_B domain, so the QSPI memory can only be used when VDD_HV_B is supplied from VCC_3.0V (default configuration). In case VDD_HV_B is reconfigured to be supplied from VCC_5.0V, then zero ohm resistors (see below table) connecting the QSPI signals from MCU to memory have to be removed.

Table 23. QSPI signal overview

MCU p	Signal name	Serial resisto r	Description
PTD11	QuadSPI_IOF A0	R316	QuadSPI serial data for serial flash device A (fast
PTD7	QuadSPI_IOF A1	R322	QuadSPI serial data for serial flash device A (fast)
PTD12	QuadSPI_IOF A2	R317	QuadSPI serial data for serial flash device A (fast)
PTC2	QuadSPI_IOF A3	R318	QuadSPI serial data for serial flash device A (fast)
PTC0	QuadSPI_IOF A4	R319	QuadSPI serial data for serial flash device A (fast)
PTD9	QuadSPI_IOF A5	R324	QuadSPI serial data for serial flash device A (fast)
PTD8	QuadSPI_IOF A6	R320	QuadSPI serial data for serial flash device A (fast)
PTC17	QuadSPI_IOF A7	R321	QuadSPI serial data for serial flash device A (fast)
PTD10	QuadSPI_SC KFA	R326	QuadSPI serial clock for serial flash device A (fas t)
PTC1	QuadSPI_DQ SFA	R325	QuadSPI data strobe signal Flash A (RWDS)
PTC3	QuadSPI_PC SFA	R327	QuadSPI chip select for serial flash device A

Zipwire

There is the Zipwire interface connector populated on the DC card. The connector type is Samtec (ERF8-005-05.0-L-DV-L-TR). There are also populated handy testpoints on Zipwire signals that are useful for debugging and performance evaluation.



The following table describes the connector.

Table 24. Zipwire interface connector description

Connector	Tag	Pin number	Signal
		1	TX_P
		2	GND
		3	TX_N
		4	GND
		5	GND
	J41	6	REF_CLK
	J 4 1	7	RX_N
		8	GND
		9	RX_P
		10 GND	GND
		11	GND
		12	GND

Signal connection to the Zipwire interface from MCU is listed in the following table.

Table 25. Zipwire interface connection to MCU

Zipwire i	Signal name	MCU port/pi n	Description
RX_N	LFAST_0_RxD_N	_	LVDS receive negative terminal
RX_P	LFAST_0_RxD_P	_	LVDS receive positive terminal
TX_N	LFAST_0_TxD_N	_	LVDS transmit negative terminal
TX_P	LFAST_0_TxD_P	_	LVDS transmit positive terminal
REF_CL	LFAST_0_EXT_REF_I /O	PTA29	LFAST reference clock input/output

Testpoints where LFAST signals can be accessed are listed in the following table.

Table 26. Test points for LFAST signals

Test point	Signal name
TP45	LFAST_0_RxD_N
TP48	LFAST_0_RxD_P
TP47	LFAST_0_TxD_N
TP44	LFAST_0_TxD_P
TP46	LFAST_0_EXT_REF_I/O

Microsecond channel

The microsecond channel (MSC) communication interface is composed of two IPs. It uses the DSPI interface with LVDS signals (data and clock signals) for upstream channel and the UART interface (only UART Rx channel) for the downstream channel.

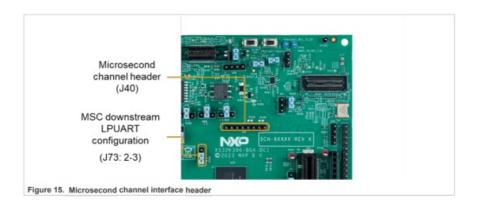
Chip select signals and UART RX are single-ended signals. Microsecond channels are available on the header J40. For using the microsecond channel, the J73 needs to be populated to position 2-3. -3 (default 1-2 to power SBC)

Table 27. Microsecond channel interface signal overview

Signal	MCU port/pa d	Description	Note
DSPI_MSC0_SC K_N	-/U16	LVDS MSC output clock negative terminal	Dedicated LVDS pad s, not multiplexed wit
DSPI_MSC0_SC K_P	-/U15	LVDS MSC output clock positiv e terminal	ity. Can be used only
DSPI_MSC0_SO UT_N	-/T14	LVDS MSC data output negative terminal	when VDD_HV_A is supplied from VCC_5 V0 because these pi
DSPI_MSC0_SO UT_P	-/U13	LVDS MSC data output positiv e terminal	ns are powered by the e VDD_HV_A.
DSPI_MSC0_PC S[0]	PTF14/ F15	DSPI MSC peripheral chip sele ct 0	_
DSPI_MSC0_PC S[1]	PTF15/ F14	DSPI MSC peripheral chip sele	_
LPUART_MSC0_ RX	PTF26/ R12	Downstream UART Rx channel	_

Table 28. J73 configuration

Functionality of PTF26	J73
LPSPI communication with FS26	1-2 (default)



Motor control interface

There is one motor control interface connector populated on the DC (see Table 31 for detailed signal description and assignment). Motor control interface is available only when VDD_HV_A is using VDD_5V0. This interface is compatible with low-voltage (GD33937) and high-voltage (GD3162) gate driver boards. The following table describes the functionality of each pin. Because the high voltage gate driver board has a bit different functionality, the differences are listed in a bold format in the table.

Caution

It is necessary to select excitation signal for the resolver by the J45.

Table 29. Motor control interface connections on DC

MCU/boa rd routin g	Function	Nam e	Pin			Name	Function	MCU/boa rd routin g
VCC_5V	Analog refer ence supply	VRE F	B1		A1	VDDA	Analog pow er supply	VDD_5V 0
AGND	Analog grou	GND A2	B2		A2	GNDA 1	Analog grou	AGND
PTE18	DC bus curr ent	A0	В3		A3	A1	Phs. U curre	PTD1

PTA8	DC bus voltage	A2	B4	A4	A3	Phs. V curre	PTE26
NC	Analog input	A4	B5	A5	A5	Phs. W curr	PTA24
NC	Analog input	A6	В6	A6	A7	Analog input	NC
NC	Analog input	A8	B7	A7	A9	Analog input	NC
PTE6	Resolver sin e negative di fferential	A10	B8	A8	A11	Resolver sin e single end ed/diff positi ve	PTE2
PTE17	Resolver co s negative di fferential	A12	В9	A9	A13	Resolver co s single end ed/diff positi ve	PTA16
NC	_	14	B10	A10	A15	Analog input / EXC_SIG_ DEN	NC
AGND	Analog grou	GND A3	B11	A11	GNDA 4	Analog grou	AGND
VDD_HV _A	Digital power suppl y MC	U_V CC	B12	A12	VCC_ PER	Digital powe	VDD_HV _A
GND	Digital groun	GND 1	B13	A13	GND2	Digital groun	GND
PTF0	U_Transistor _ Temp_H/E ncoder_A	TM0	B14	A14	PWM0	PWM Phs U H	PTD24

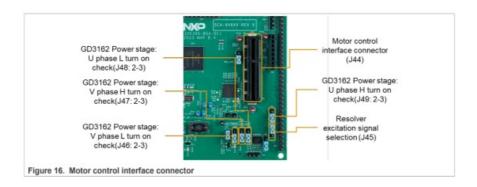
PTF9	U_Transistor _ Temp_L/E ncoder_B	TM1	B15	A15	PWM1	PWM Phs U L	PTA2
PTF4	V_Transistor _Temp_ L/E ncoder_Inde x	TM2	B16	A16	PWM2	PWM Phs V	PTA3
PTF5	V_Transistor _ Temp_H	ТМЗ	B17	A17	PWM3	PWM Phs V	PTD23
PTE27	W_Transisto r_ Temp_L	TM4	B18	A18	PWM4	PWM Phs W	PTD2
PTB12/S WG0	Resolver exc itation	TM5	B19	A19	PWM5	PWM Phs W	PTD3
PTF14	Run button	IO1	B20	A20	PWM6	U_GS disch arge	PTE19
PTA20	SPI_MISO	MISO	B21	A21	PWM7	U_GS Charge/ Bra ke PWM	PTB2
PTA18	SPI_MOSI	MOSI	B22	A22	PWM8	V_GS Disch arge/ Zero C ross Phase U	PTA30
PTA19	SPI_SCK	SCKL	B23	A23	PWM9	V_GS Charg e/Zero cross Phase V	PTB18

PTA21	SPI CS Low/ SPI CS	/SS	B24	A24	PWM1 0	W_GS Disc harge/ Zero cross Phase W	PTB21
PTA17	W_Transisto r_ Temp_H	IO2	B25	A25	PWM1	W_GS Char ge	PTA31
PTG3	W_Transisto r_ turnon_ch eck_ H/UAR T TXD	SCI_ TXD	B26	A26	FAULT 1	INTB_HS/Fa ult_OC	PTB15
PTG8	W_Transisto r_ turnon_ch eck_ L/UAR T RXD	SCI_ RXD	B27	A27	FAULT 2	INTB_LS/Fa ult_OV	PTB16
PTA14	Fail safe ena ble/ GD ena ble	IO3	B28	A28	FAULT 3	U_Transistor _ turnon_ch eck_H	PTD20
PTA23	Fail state lo w side/GD R eset	104	B29	A29	FAULT 4	U_Transistor _ turnon_ch eck_L	PTB17
PTG4	Fail state hig h side/GD IN T	IO5	B30	A30	IO6	SPI CS High	PTA22
VCC_12 V	12V power s upply	VPO WER	B31	A31	IO7	V_Transistor _ turnon_ch eck_ H/SW_ UP	PTB5

GND	Digital GND/ Power GND	GND P	B32		A32	IO8	V_Transistor _ turnon_ch eck_ L/SW_ Down	PTB13
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Table 30. Resolver excitation signal selection

Source of the resolver excitation signal	J45
Sine Wave Generator 0	1-2
eTPU_B_CH[2]/eTPU_A_[0]/GPIO pin	2-3



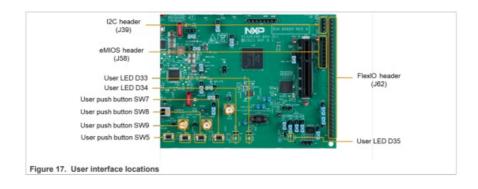
User interface

There are several pin headers where multiple signals are available as well as three user LEDs and four push buttons.

Table 31. User interface summary

Module	DC reference	Description
I2C	J39	LPI2C1 interface
FlexIO	J62	32 signals of FlexIO accessible on the header
eMIOS0	J58	8 signals of eMIOS accessible on headers
	D35	PTH7 MCU port configured as GPIO
		1

User LED	D34	PTD4 MCU port configured as GPIO						
	D33	PTD5 MCU port configured as GPIO						
	SW5	PTE21 MCU port configured as GPIO. J71 needs to be shorted to position 2-3 to select the SW5 functionality.						
User push buttons	SW7	PTG2 MCU port configured as GPIO						
	SW8	PTG1 MCU port configured as GPIO						
	SW9	PTG0 MCU port configured as GPIO						



Battery management interface

There are populated MC33664ATL1EG isolated network high-speed transceivers for communication with the battery subsystem. The MCU communicates with the device through two LPSPI interfaces (LPSPI2 – master, LPSPI3 – slave) and two GPIO pins. The battery management (BMS) interface is using the header J59.

Table 32. BMS interface signal overview

Module	Functionalit y	MCU port	Description
	SCK	PTF0	
LPSPI2	PCS0	PTF3	Upstream communication
	SOUT	PTF2	

GPIO	EN	PTH11	Control the BMS device mode (Normal/Sleep)				
	SCK	PTF13					
LPSI3	PCS0	PTF16	Downstream communication				
	SIN	PTF12					
GPIO	INT	PTH12	BMS interrupt to trigger the device wake up				

Monitoring of the internal signal

The TRGMUX_APP module includes the possibility to monitor the internal triggers over the pins. On the EVB is accessible 9 from 16 TRGMUX outputs as shown in the following table.

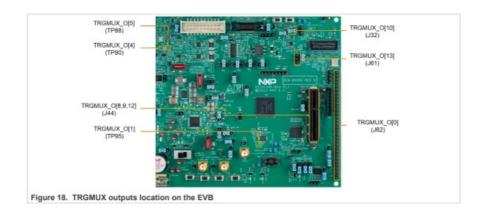
To route the internal signals to the pins, the following needs to be configured:

- Output functionality of the pin as TRGMUX output in the SIUL2 module (SIUL2.MSCR[x].B.SSS)
- Output buffer enabled in the SIUL2 module (SIUL2.MSCR[x].B.OBE)
- Selected signal needs to be configured in the TRGMUX_AP module based on the selection done based on the S32K39_and_S32K37_TRMUX_connectivity.xlsx/S32K36_TRMUX_connectivity.xlsx spread sheet attached to the RM Also the eTPU signals can be routed over the TRGMUX_APP on the pins but for that you need to route them to the TRGMUX_APP (signals TRGMUX_MSC_TRGMUX_IN0 TRGMUX_MSC_TRGMUX_IN9) by configuring TRGMUX_MSC (registers TRGMUX_APP_TRGMUX_OUT0 TRGMUX APP_TRGMUX OUT9)
- TRGMUX_APP number of input signals are limited to 128 and for expanding them, the monitor mux functionality is used that routes additional internal signals to the TRGMUX_APP to the inputs 2, 3, and 4 by configuring the monitor mux registers place in the SIUL2 module (MUX0_TIMER_EN1, MUX0_BCTU1_EN, MUX1_TIMER_EN0, MUX1_BCTU0_EN, MUX1_MISC_EN, MUX2_TIMER_EN1, MUX2_BCTU1_EN, MUX2_MISC_EN). These signals are listed in the Monitor Mux sheet of the spreadsheet mentioned above. If you want to have one internal signal on

the TRGMUX_APP input, you need to set only one bit in the specific MUX register because these signals are ORed before entering the TRGMUX_APP input.

Table 33. TRGMUX_OP output signal summary

TRGMUX_O UTPUT	Port pin	Board ro uting	MSCR	MSCR[SSS]	TRGMUX _ APP reg ister	TRGMUX_A PP register SEL bitfield number
0	PTE5	J62.8	133	0x8	SIUL_OU	0
1	PTD0	TP95	96	0x7	T_0 (32)	1
4	PTE1	TP90	138	0x7	SIUL_OU	0
5	PTE1	TP88	139	0x7	T_1 (33)	1
8	PTA3	J44.A25	31	0x7		0
9	PTB1	J44.A23	50	0x7	SIUL_ OU T_2 (34)	1
10	PTB1	J32.2	51	0x7		2
12	PTB2	J44.A24	53	0x7	SIUL_OU	0
13	PTB2 2	J61.3	54	0x7	T_3 (35)	1



Default jumper configuration

Table 34. Default jumper configuration

Module	Function ality	DCre feren ce	Default connec tion	Description	
	VCC_12	J3	1-2	Main supply is sourced from DC card conne ctors, provided either from J1 or J2.	
Input po wer distri bution	VCC_5V	J4	1-2	Supplied from external power screw connector (JP1 pin 4).	
	VCC_1V 5	J6	1-2	Supplied from external power screw connector (JP1 pin 2).	
	VCC_3V	J7	1-2	Supplied from external power screw connector (JP1 pin 3).	
	VDD_HV _B	R334	1-2	Supplied from VCC_3V3.	
	VDD_HV _A	R6	1-3	Supplied from VCC_5V0.	
	Debug m	J10	Closed	Debug pin is connected to positive voltage t o enable Debug mode.	

FS26 PM	ode			Left open when configuring FS26 for a debu			
1		J11	Open	g mode.			
	Reset/W ake	J12	Closed	RESET_b signal connected to WAKE2 and RSTB pins of FS26.			
	SPI interf	J71	1-2	PTE21 routed to FS26 as SIN			
		J73	1-2	PTF26 routed to FS26 as PCS1			
		J75	2-3	PTC11 routed to FS26 as SOUT			
	Select th e interfac e	J16	2-4	Arm JTAG connector selected for TDI signature.			
		J17	2-4	Arm JTAG connector selected for TMS signal.			
		J18	2-4	Arm JTAG connector selected for TCK sign I.			
Debug		J19	2-4	ARM JTAG connector selected for TDO sign al.			
	Power	J21	Closed	VDD_HV_A connected to pin 2 of Arm JTA G debug connector.			
	Reset	J22	Closed	RESET_b signal connected to Arm ETM Mi ctor trace connector.			
		J23	Closed	RESET_b signal connected to Arm JTAG debug connector.			
		J68	Open	Keep this jumper open			
	VDD_1V 5	J26 Open		Sourced from external source, not from MC U internal SMPS.			

MCU po wer	NMOS g ate contr	J27	2-3	NMOS_CTRL signal from MCU connected to the gate of external NFET to regulate 1.1 V core and logic supply down from 1.5V.
	PMOS gate cont rol	J28	1-2	Gate of the P-MOS is shorted to the VDD_ DCDC. PMOS_CTRL is left open.
	VDD_DC DC	J29	2-3	Sourced from VDD_HV_B.
	VDD_LV DS	J30	2-3	Sourced from VDD_HV_B.

Abbreviations

MCU - Microcontroller Unit

EVB - Evaluation Board

DC - Daughter Card

MB - Motherboard card

PMIC - Power Management Integrated Circuit

ESD - Electrostatic Discharge

PHY - Physical interface

SMPS – Switched-Mode Power Supply

USB - Universal Serial Bus

MSC - Microsecond Channel

BMS - Battery Management System

Revision history

Revision history

Document ID	Release date	Description
UM12212 v.1.0	03 February 2025	Initial release

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NXP S32K396 Motor Control Development Kit [pdf] User Manual S32K396-BGA-DC1, S32K396 289MapBGA, S32K396 Motor Control Development Kit, S32K396, Motor Control Development Kit, Control Development Kit, Development Kit

References

- User Manual
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